L Number	Hits	Search Text	DB	Time stamp
-	215	yuji.in. and kamikawa.in.	USPAT;	2003/06/23 14:02
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
- ·	166	(yuji.in. and kamikawa.in.) and (wafer or semiconductor	USPAT;	2003/06/19 09:48
		or substrate)	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
١.			IBM_TDB	
-	65	((yuji.in. and kamikawa.in.) and (wafer or semiconductor	USPAT;	2003/06/19 10:24
		or substrate)) and rota\$5	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3638	134/57R,63,66,153,158,161,902.ccls.	USPAT;	2003/06/23 13:21
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		•	IBM TDB	
_	1884	134/57R,63,66,153,158,161,902.ccls. and (substrate or	USPAT;	2003/06/23 13:21
		wafer or semiconductor)	US-PGPUB;	
]			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
-	1307	(134/57R,63,66,153,158,161,902.ccls. and (substrate or	USPAT;	2003/06/19 10:26
	, 55,	wafer or semiconductor)) and (chamber or tank or vessel)	US-PGPUB;	2000/00/10 10:20
		Training of commontances by and (chambor of talls of vocasily	EPO; JPO;	
		,	DERWENT:	
,			IBM_TDB	
_	635	((134/57R,63,66,153,158,161,902.ccls. and (substrate or	USPAT;	2003/06/23 12:05
_	000	wafer or semiconductor)) and (chamber or tank or	US-PGPUB;	2000/00/20 12:00
		vessel)) and (rotary or rotat\$5)	EPO; JPO;	
		(vocas), and (vocas) or vocasos,	DERWENT;	
			IBM_TDB	
_	345	(((134/57R,63,66,153,158,161,902.ccls. and (substrate or	USPAT;	2003/06/23 12:07
		wafer or semiconductor)) and (chamber or tank or	US-PGPUB;	2000/00/20 12:07
	•	vessel)) and (rotary or rotat\$5)) and (vertical\$2 and	EPO; JPO;	•
		horizontal\$2)	DERWENT;	
			IBM_TDB	
_	128	(((((134/57R,63,66,153,158,161,902.ccls. and (substrate	USPAT;	2003/06/23 13:24
	120	or wafer or semiconductor)) and (chamber or tank or	US-PGPUB:	2000/00/20 10.24
		vessel)) and (rotary or rotat\$5)) and (vertical\$2 and	EPO; JPO;	,
		horizontal\$2)) and ((transfer or robot\$2) with arm)	DERWENT:	
			IBM TDB	
_	323	((118/52,53.ccls. and (substrate or wafer or	USPAT;	2003/06/23 14:09
	020	semiconductor)) and (chamber or tank or vessel)) and	US-PGPUB;	2000/00/20 14.08
		(rotary or rotat\$5)	EPO; JPO;	
		(Totaly of Totalwo)	DERWENT;	
			IBM TDB	
_	172	(((118/52,53.ccls. and (substrate or wafer or	USPAT;	2003/06/23 12:08
	172	semiconductor)) and (chamber or tank or vessel)) and	US-PGPUB;	2000/00/20 12.00
İ		(rotary or rotat\$5)) and (vertical\$2 and horizontal\$2)	EPO; JPO;	
		(Totaly of Totalwo)) and (verticaloz and nonzontaloz)		
-			DERWENT;	
	78	////118/52.53 colo and (substrata ar wafar ar	IBM_TDB `	2002/06/22 40:40
-	./0	((((118/52,53.ccls. and (substrate or wafer or	USPAT;	2003/06/23 12:40
1		semiconductor)) and (chamber or tank or vessel)) and	US-PGPUB;	
		(rotary or rotat\$5)) and (vertical\$2 and horizontal\$2)) and	EPO; JPO;	
		((transfer or robot\$2) with arm)	DERWENT;	
			IBM_TDB	

			T	
-	3638	134/57R,63,66,153,158,161,902.ccls.	USPAT;	2003/06/23 13:21
			US-PGPUB;	
			EPO; JPO;	
	,		DERWENT;	
	140	104/570 00 00 450 450 404 000	IBM_TDB	
- '	112	134/57R,63,66,153,158,161,902.ccls. and (substrate or	USPAT;	2003/06/23 14:03
		wafer or semiconductor) and rotor	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	25	(124/E7D 62 66 452 459 464 002 colo. and /outhatrata ar	IBM_TDB	2002/06/22 44:02
-	35	(134/57R,63,66,153,158,161,902.ccls. and (substrate or	USPAT;	2003/06/23 14:02
		wafer or semiconductor) and rotor) and ((transfer or	US-PGPUB;	
		robot\$2) with arm)	EPO; JPO;	
			DERWENT;	
	1620	(take and electron and limited) as	IBM_TDB	2002/06/22 44:02
] -	1620	(tokyo and electron and limited) as.	USPAT;	2003/06/23 14:02
		•	US-PGPUB;	
			EPO; JPO;	
		•	DERWENT; IBM_TDB	
	568	((tokyo and electron and limited) as) and ((transfer or	USPAT;	2003/06/23 14:02
-	300	robot\$2) with arm)	US-PGPUB;	2003/00/23 14.02
		1000(\$2) With airin	EPO, JPO;	
			DERWENT;	
		·	IBM_TDB	
1_	10	(((tokyo and electron and limited).as.) and ((transfer or	USPAT;	2003/06/23 14:03
		robot\$2) with arm)) and (substrate or wafer or	US-PGPUB;	2000/00/20 14:00
		semiconductor) and rotor	EPO; JPO;	
			DERWENT:	
			IBM_TDB	
_	1960	118/500,501.ccls.	USPAT;	2003/06/23 14:09
			US-PGPUB	2000/00/20 11:00
-			EPO; JPO;	
	-		DERWENT:	
			IBM_TDB	
-	343	((118/500,501.ccls. and (substrate or wafer or	USPAT;	2003/06/23 14:11
		semiconductor)) and (chamber or tank or vessel)) and	US-PGPUB;	
		(rotary or rotat\$5)	EPO; JPO;	
		, ,	DERWENT;	
			IBM_TDB	
-	24	(((118/500,501.ccls. and (substrate or wafer or	USPAT;	2003/06/23 14:11
		semiconductor)) and (chamber or tank or vessel)) and	US-PGPUB;	
		(rotary or rotat\$5)) and rotor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	